IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type Distribute						rials and M	ials and Mfg Information				
Supplier	r Information															
Company name*				ompany unique ID			Unique ID Authority					Respon	Response Date*			
On Semice	onductor											2021-02	2021-02-04			
Contact N	ame	Title - Contact			1	Phone - Contact*					Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*						
Product-I	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturing		facturing Site	Weight*		U	OM	Unit Type		
		MOC207M 8SO TR		8SO TR			2021-02-04			LITE	LITEONFG		168.5863	36 m	g	Each
Manufa	cturing Proccess Informat	tion								,				1		
	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-020 M		-STD-020 MSI	L Rating	Peak Process Body		Body Tempe	y Temperature Max Time at Peak		Temperature Number of Refle		eflow Cycle	S	
Matte Tin (Sn) - annealed		CU Alloy 1			260		C	3	30		nds 3					
Comments																
evel 1 - m	aximum time at peak temperatu	re during sol	dering is 10-3	0 seconds												
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	neous Material Weight Unit of Measure Level Substance		Substance	CAS		Weight	Unit of Measure	
Coupling Gel	4.18236	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.046	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		4.1364	mg
Die	4.043	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.283	mg
			Supplier	Silicon (Si)	7440-21-3		3.76	mg
Die Attach	0.754	mg	Supplier	Silver (Ag)	7440-22-4		0.6032	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.1508	mg
Lead Frame	59.197	mg	Supplier	Silver (Ag)	7440-22-4		0.148	mg
			Supplier	Zinc (Zn)	7440-66-6		0.071	mg
			Supplier	Iron (Fe)	7439-89-6		1.36	mg
			Supplier	Copper (Cu)	7440-50-8		57.6	mg
			Supplier	Phosphorus (P)	7723-14-0		0.018	mg
Mold Compound-White	98.06	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		3.92	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		23.5	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		2.94	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		67.7	mg
Plating	2.1	mg	Supplier	Tin (Sn)	7440-31-5		2.1	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5		0.25	mg